

ABSTRACT

A WAFER TABLE FOR
DIE BONDING APPARATUS

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Die bonding apparatus is provided in which in order to move a target die to a pick-up position, a wafer table is moved by rotation and along one linear axis. This reduces the footprint of the apparatus in comparison to prior art apparatus in which this movement is accomplished by movement along two orthogonal linear axes. In an embodiment of the invention, however, movement along a second orthogonal linear axis may also be provided whereby a user may select the method of moving a target die to the pick-up position.

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FIG. 3